To the Honorable Commissioner of Patents.

1. Name of conveying party(ies):
   Yoshitaka SASAGO
   Takashi KOBAYASHI
   06/11/02

2. Name and address of receiving party(ies):
   Name: Hitachi, Ltd.
   Address: 6, Kanda Surugadai 4-chome
            Chiyoda-ku
   City: Tokyo
   Country: Japan

3. Nature of conveyance:
   ☑ Assignment
   ☐ Merger
   ☐ Security Agreement
   ☐ Change of Name
   ☐ Other

   Execution Date: May 22, 2002

4. Application number(s) or patent numbers(s):
   10/166145
   Patent Application No. 06/14/2002 EFIDES 00000074 10166145
   04 FC:581 40.00 DP

   B. Patent No.(s)

5. Name and address of party to whom correspondence concerning document should be mailed:
   Name: Mitchell W. Shapiro
   Registration No. 31,568
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            1751 Pinnacle Drive
            Suite 500
   City: McLean
   Country: US
   ZIP: 22102-3833
   State/Prov.: VA

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): $ 40.00
   ☑ Enclosed - Any excess or insufficiency should be credited or debited to deposit account
   ☐ Authorized to be charged to deposit account

8. Deposit account number:
   50-1165
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   To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.
   Mitchell W. Shapiro
   Name of Person Signing
   June 11, 2002
   Signature

Total number of pages including cover sheet, attachments, and mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments

PATENT
REEL: 012990 FRAME: 0163
As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar ($1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

NONVOLATILE SEMICONDUCTOR MEMORY DEVICE AND MANUFACTURING METHOD THEREOF

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)

Date Signed

1) Yoshitaka SASAGO

05/22/2002

2) Tabashi KITAYASHI

05/22/2002

3) Takashi KOBAYASHI

4) 

5) 

6) 

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RECORDED: 06/11/2002

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